**Version with markings to show changes made**

In the specification:

This application claims priority under 35 USC [is] as a continuation-in-part of U.S. Patent Application Serial No. 09/741,535, filed on December [29] 19, 200, the entire contents of which are hereby incorporated by reference.

In the claims:

Claims 1, 6, 10 and 13 have been amended as follows:

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1. A device comprising:

a lead frame having conductive leads and an insulative composition interposed between the leads;

a die having a lower die surface that [overlies a first region of the lead frame,] is connected by contacts to the lead frame, and is spaced by a gap from [the] a first region of the lead frame; and

a polymer composition that forms a continuous network that forms a layer that extends at least above the lower die surface and covers regions of the lead frame surface that are outside the first region and are not occupied by any component.

6. A device comprising:

a conductive substrate;

a die having a lower die surface that [opposes a first region of the substrate,] is connected by contacts to the substrate, and is spaced by a gap from [the first region] the substrate; and

a polymer composition that forms a network on a region of the substrate that extends at least above the lower die surface, the layer imparting sufficient rigidity to

the device to maintain integrity of the contacts during etching of the substrate in the absence of a supporting frame.

10. A device comprising:

a lead frame;

a die having a lower die surface that [overlies,] is connected by contacts to, and is spaced by a gap from a first region of the lead frame;

a peripheral component also connected to the lead frame at a location other than in the first region; and

a polymer composition that extends in a direction normal to the lead frame at least above the lower die surface and extends along a surface of the lead frame from the die to the peripheral component.

13. A method comprising:

[a) forming a gap between a die and a substrate to which the die is connected;]

[b] a) causing a compound to enter [the] a gap between a substrate and a die connected to the substrate and to form a layer on an upper surface of the substrate; and

[c] b) setting the compound to generate a continuous, rigid network that extends within the gap and forms a layer surrounding the die perimeter.

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